



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





# DE2703600L

## Silicon epitaxial planar type

For ESD protection  
DE2S036 in SSSMini2 type package

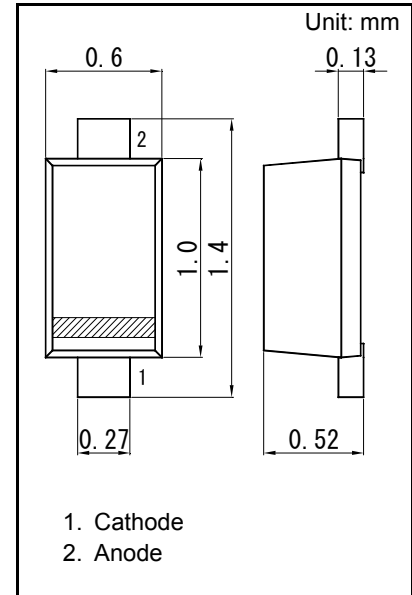
■ Features

- High ESD
- Halogen-free / RoHS compliant  
(EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol:6C

■ Packaging

Embossed type (Thermo-compression sealing) 10 000 pcs / reel (standard)

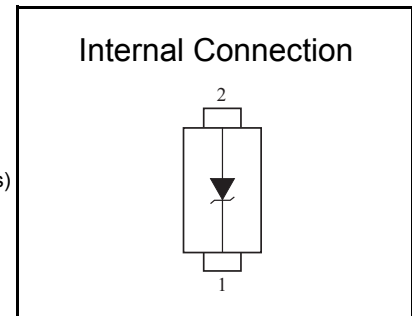


Panasonic	SSSMini2-F4-B
JEITA	SC-104A
Code	SOD-723

■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Total power dissipation <sup>*1</sup>	PT	120	mW
Electrostatic discharge <sup>*2</sup>	ESD	±30	kV
Junction temperature	Tj	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +150	°C

Note) \*1: Mounted on glass epoxy print board. ( 45 mm x 45 mm x 1 mm)  
Solder in ( 0.4 mm x 0.3 mm)  
\*2: Test method:IEC61000\_4\_2(C = 150 pF,R = 330 Ω, Contact discharge:10 times)

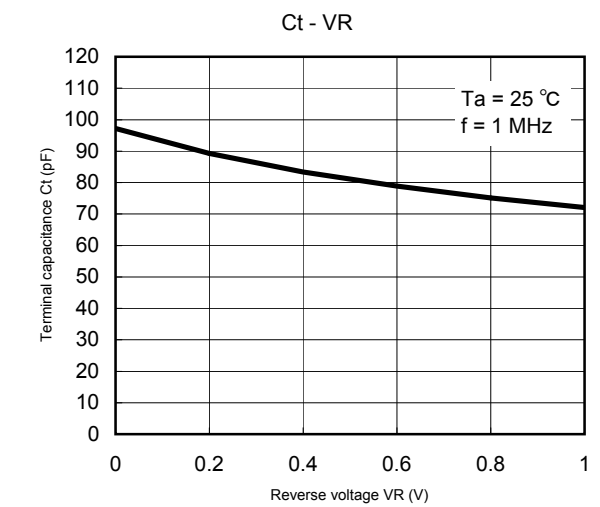
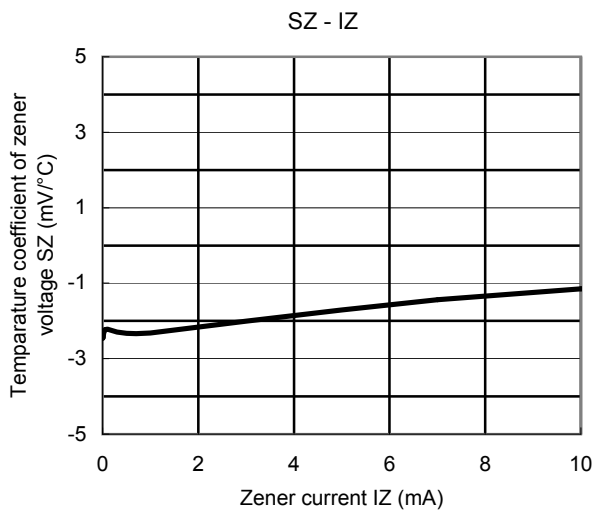
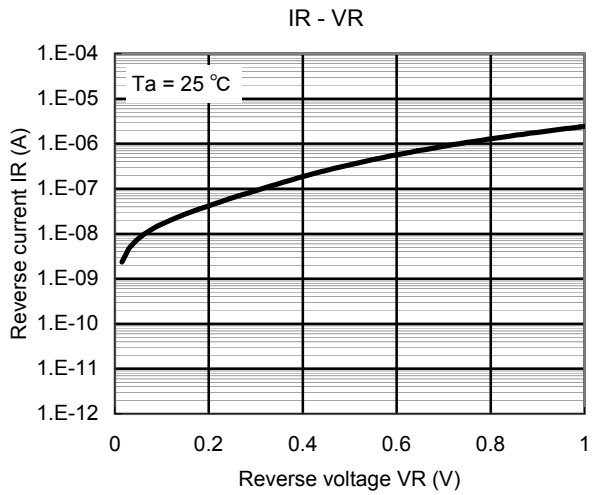
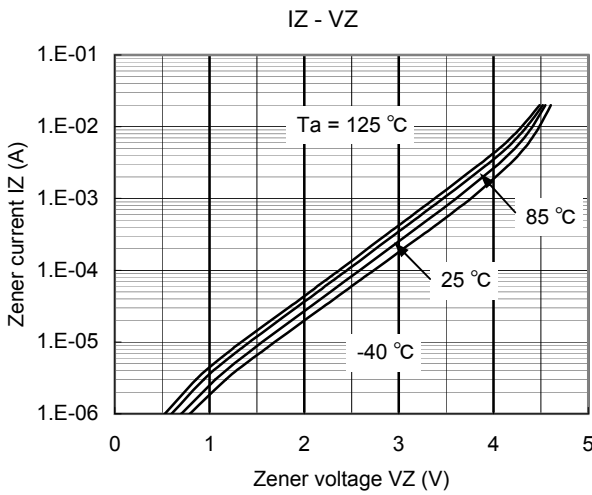
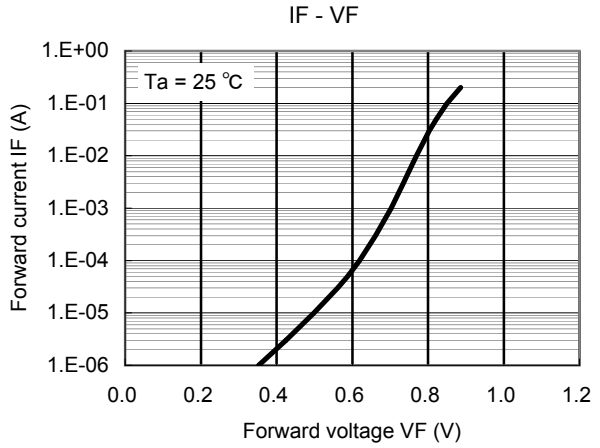
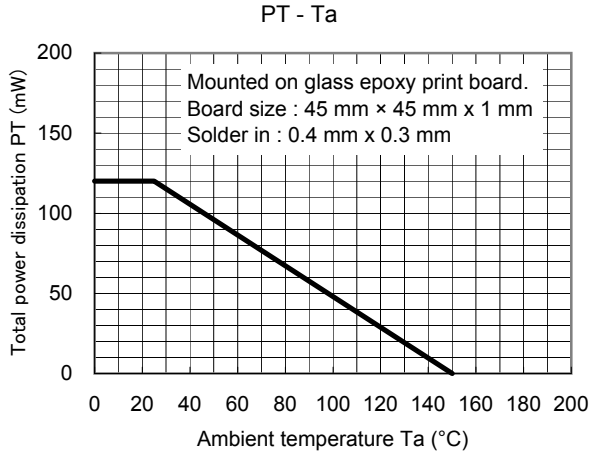


■ Electrical Characteristics Ta = 25 °C ± 3 °C

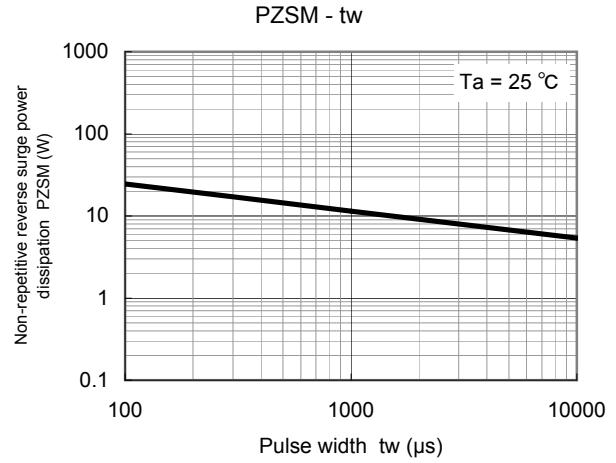
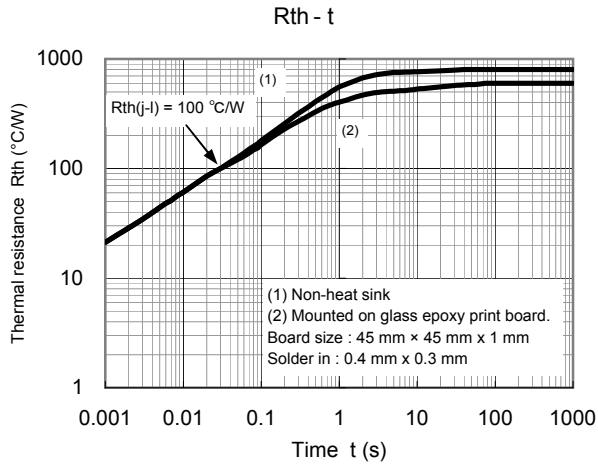
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Zener voltage <sup>*1,*2</sup>	VZ	IZ = 1 mA	3.42		3.78	V
Reverse current	IR	VR = 1 V			10.0	μA
Terminal capacitance	Ct	VR = 0V, f = 1 MHz		97		pF
Temperature coefficient of zener voltage <sup>*3</sup>	SZ	IZ = 1 mA		-2.3		mV/°C

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.  
2. \*1: The temperature must be controlled 25°C for VZ measurement.  
VZ value measured at other temperature must be adjusted to VZ (25°C)  
\*2: VZ guaranteed 20 ms after current flow.  
\*3: Tj = 25°C to 150°C

Technical Data ( reference )

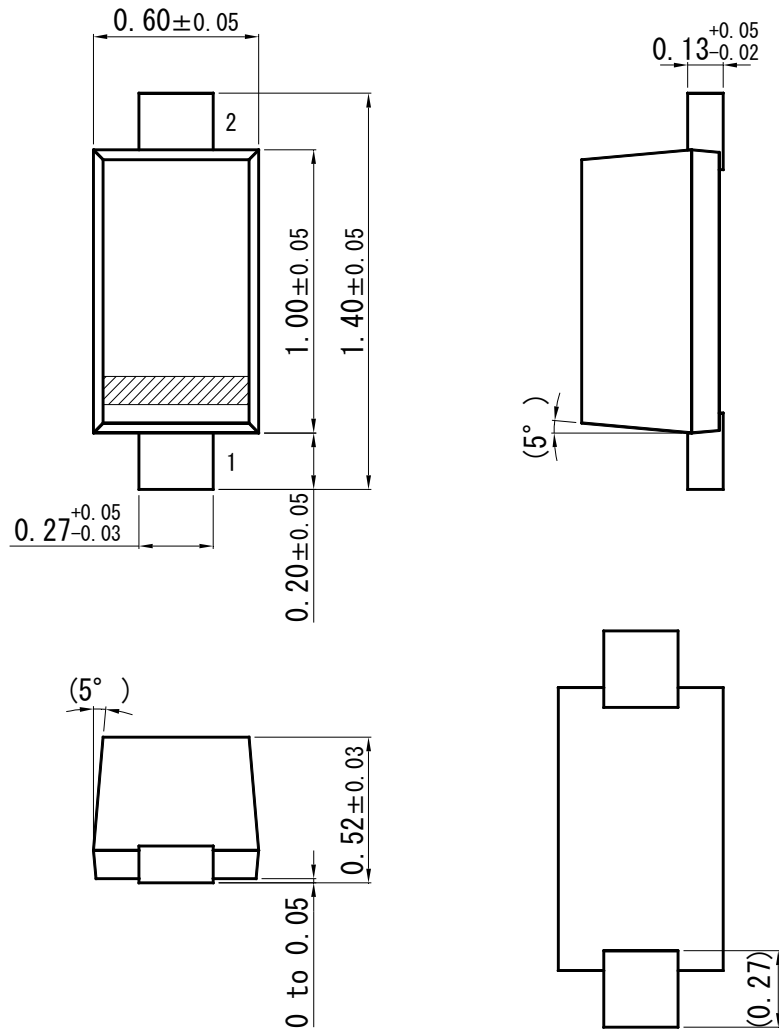


Technical Data ( reference )

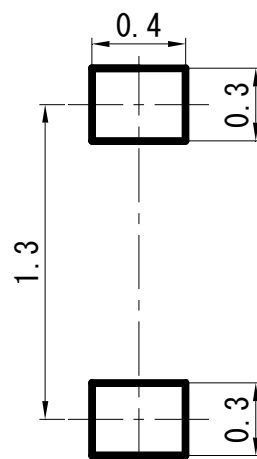


SSSMini2-F4-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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